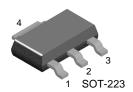


PZTA29 NPN Darlington Transistor

- This device designed for applications requiring extremely high current gain at collector currents to 500mA.
- Sourced from process 03.



1. Base 2.4. Collector 3. Emitter

Absolute Maximum Ratings * T_a = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V _{CES}	Collector-Emitter Voltage	100	V
V _{CBO}	Collector-Base Voltage	100	V
V _{EBO}	Emitter-Base Voltage	12	V
I _C	Collector Current - Continuous	800	mA
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C

^{*}These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Electrical Characteristics T_a = 25°C unless otherwise noted

Symbol	Parameter	Conditions	Min.	Max	Units
Off Character	ristics				
V _{(BR)CES}	Collector-Emitter Breakdown Voltage	$I_C = 100\mu A, V_{BE} = 0$	100		V
V _{(BR)CBO}	Collector-Base Breakdown Voltage	$I_C = 100\mu A, I_E = 0$	100		V
V _{(BR)EBO}	Emitter-Base Breakdown Voltage	$I_E = 10\mu A, I_C = 0$	12		V
I _{CBO}	Collector Cutoff Current	V _{CB} = 80V, I _E = 0		100	nA
I _{CES}	Collector Cutoff Current	V _{CE} = 80V, V _{BE} = 0		500	nA
I _{EBO}	Emitter Cut-off Current	V _{EB} = 10V, I _C = 0		100	nA
On Character	istics	•			
h _{FE}	DC Current Gain	V _{CE} = 5.0V, I _C = 10mA V _{CE} = 5.0V, I _C = 100mA	10,000 10,000		
V _{CE(sat)}	Collector-Emitter Saturation Voltage	I _C = 10mA, I _B = 0.01mA I _C = 100mA, I _B = 0.1mA		1.2 1.5	V V
V _{BE(on)}	Base-Emitter On Voltage	I _C = 100mA, V _{CE} = 5.0V		2.0	V
	characteristics	•			
f _T	Current Gain Bandwidth Product	I _C = 10mA, V _{CE} = 5.0V, f = 100MHz	125		MHz
C _{obo}	Output Capacitance	V _{CB} = 1.0V, I _E = 0, f = 1.0MHz		8.0	pF

^{*} Pulse Test: Pulse Width $\leq 300 \mu s,$ Duty Cycle $\leq 2.0\%$

^{1.} These ratings are based on a maximum junction temperature of 150 degrees ${\sf C}.$

 $^{2. \} These \ are \ steady \ limits. \ The \ factory \ should \ be \ consulted \ on \ application \ involving \ pulsed \ or \ low \ duty \ cycle \ operations$

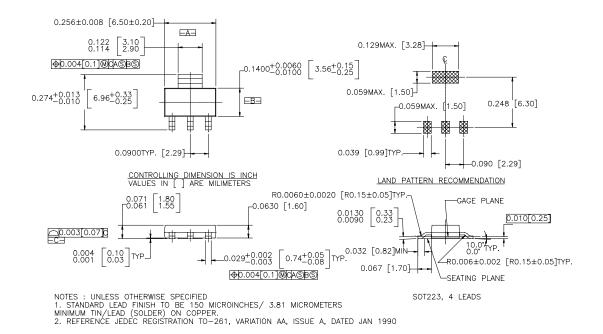
Thermal Characteristics $T_a = 25$ °C unless otherwise noted

Symbol	Parameter	Max.	Units
P _D	Total Device Dissipation Derate above 25°C	1,000 8.0	mW mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	125	°C/W

^{*} Device mounted on FR-4PCB 36mm \times 18mm \times 1.5mm; mounting pad for the collector lead min. 6cm 2

Mechanical Dimensions

SOT-223



Dimensions in Millimeters

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